

# MURS205T3, MURS210T3

Preferred Device

## Surface Mount Ultrafast Power Rectifiers

Ideally suited for high voltage, high frequency rectification, or as free wheeling and protection diodes in surface mount applications where compact size and weight are critical to the system.

### Features

- Small Compact Surface Mountable Package with J-Bend Leads
- Rectangular Package for Automated Handling
- High Temperature Glass Passivated Junction
- Low Forward Voltage Drop (0.74 V Max @ 2.0 A,  $T_J = 150^\circ\text{C}$ )
- Pb-Free Packages are Available

### Mechanical Characteristics:

- Case: Epoxy, Molded
- Weight: 95 mg (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes:  $260^\circ\text{C}$  Max. for 10 Seconds
- Polarity: Polarity Band Indicates Cathode Lead

### MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	$V_{RRM}$ $V_{RWM}$ $V_R$	50 100	V
Average Rectified Forward Current @ $T_L = 150^\circ\text{C}$ @ $T_L = 125^\circ\text{C}$	$I_{F(AV)}$	1.0 2.0	A
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	$I_{FSM}$	50	A
Operating Junction Temperature	$T_J$	-60 to +175	$^\circ\text{C}$

### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Lead ( $T_L = 25^\circ\text{C}$ )	$R_{\theta JL}$	13	$^\circ\text{C/W}$

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.



ON Semiconductor®

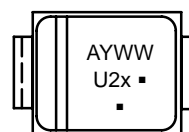
<http://onsemi.com>

## ULTRAFAST RECTIFIERS 2 AMPERES, 50-100 VOLTS



SMB  
CASE 403A

### MARKING DIAGRAM



A = Assembly Location  
Y = Year  
WW = Work Week  
U2x = Device Code  
x = A for MURS205T3  
= B for MURS210T3

■ = Pb-Free Package

(Note: Microdot may be in either location)

### ORDERING INFORMATION

Device	Package	Shipping†
MURS205T3	SMB	2500 Tape & Reel
MURS205T3G	SMB (Pb-Free)	2500 Tape & Reel
MURS210T3	SMB	2500 Tape & Reel
MURS210T3G	SMB (Pb-Free)	2500 Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Preferred devices are recommended choices for future use and best overall value.

# MURS205T3, MURS210T3

## ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Maximum Instantaneous Forward Voltage (Note 1) ( $i_F = 2.0$ A, $T_J = 25^\circ\text{C}$ ) ( $i_F = 2.0$ A, $T_J = 150^\circ\text{C}$ )	$v_F$	0.94 0.74	V
Maximum Instantaneous Reverse Current (Note 1) (Rated dc Voltage, $T_J = 25^\circ\text{C}$ ) (Rated dc Voltage, $T_J = 150^\circ\text{C}$ )	$i_R$	2.0 50	$\mu\text{A}$
Maximum Reverse Recovery Time ( $i_F = 1.0$ A, $di/dt = 50$ A/ $\mu\text{s}$ ) ( $i_F = 0.5$ A, $i_R = 1.0$ A, $I_R$ to 0.25 A)	$t_{rr}$	30 20	ns
Maximum Forward Recovery Time ( $i_F = 1.0$ A, $di/dt = 100$ A/ $\mu\text{s}$ , Rec. to 1.0 V)	$t_{fr}$	20	ns

1. Pulse Test: Pulse Width = 300  $\mu\text{s}$ , Duty Cycle  $\leq 2.0\%$ .

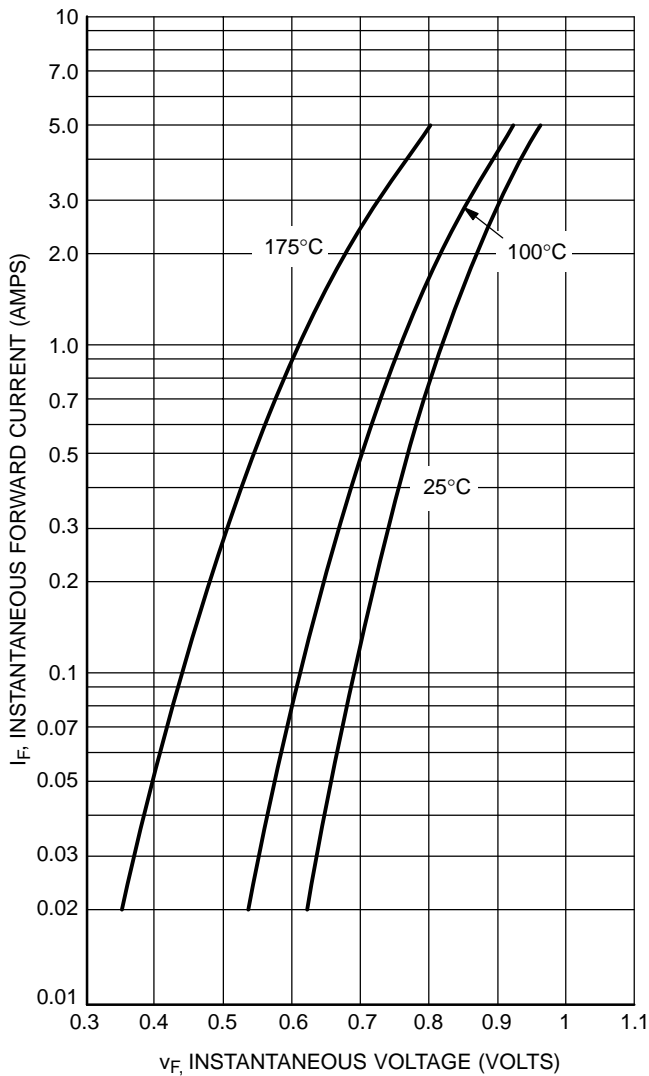


Figure 1. Typical Forward Voltage

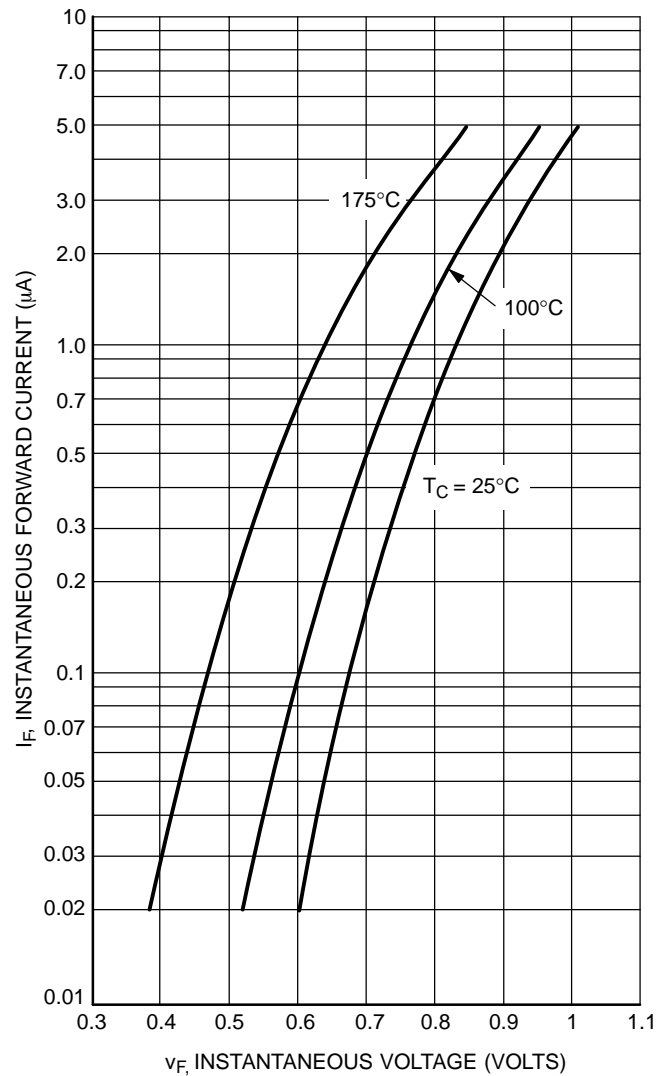


Figure 2. Maximum Forward Voltage

# MURS205T3, MURS210T3

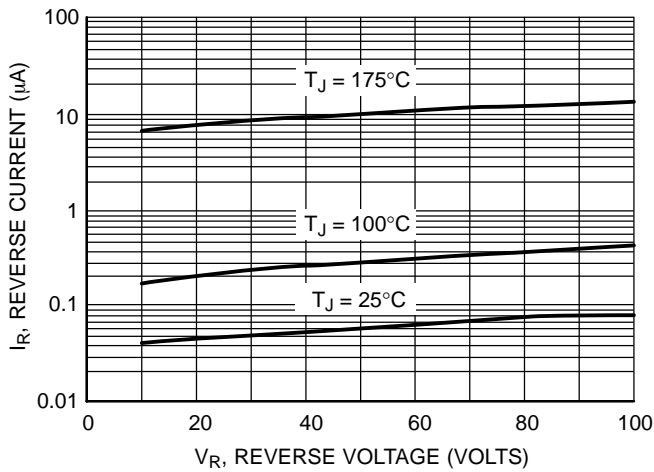


Figure 3. Typical Reverse Current\*

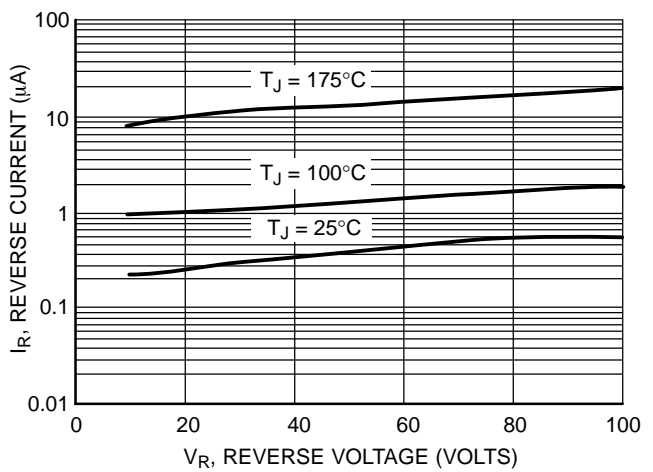


Figure 4. Maximum Reverse Current\*

\* The curves shown are typical for the highest voltage device in the voltage grouping. Typical reverse current for lower voltage selections can be estimated from these same curves if applied  $V_R$  is sufficiently below rated  $V_R$ .

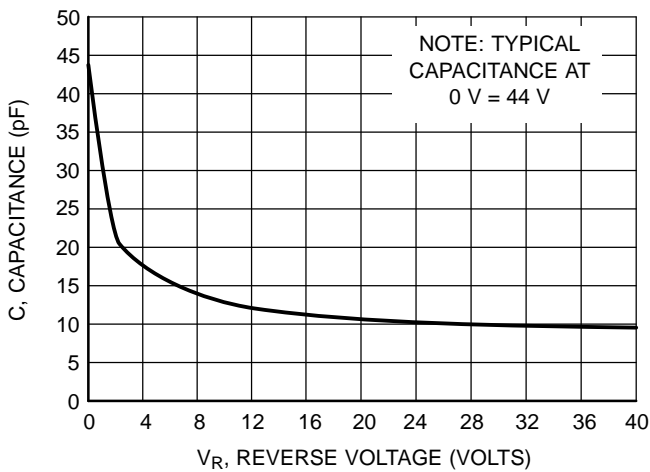


Figure 5. Typical Capacitance

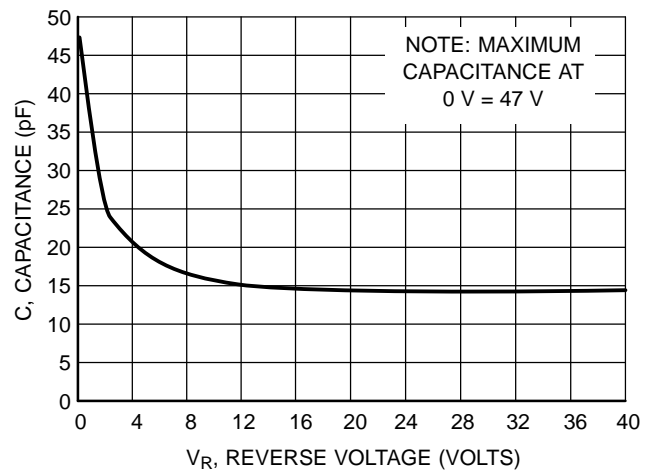


Figure 6. Maximum Capacitance

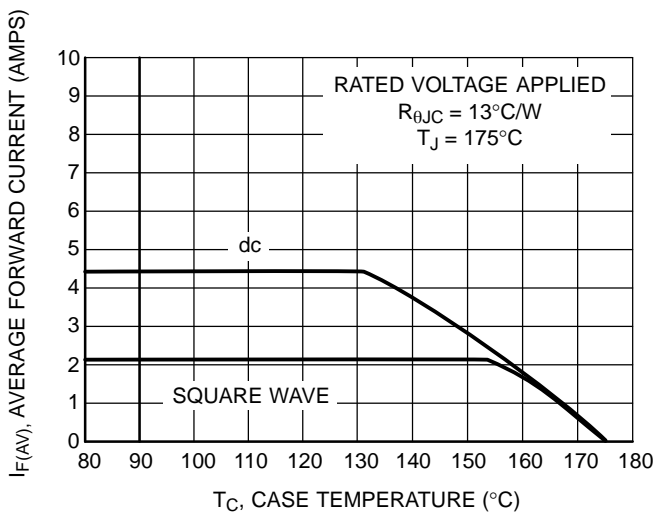


Figure 7. Current Derating, Case

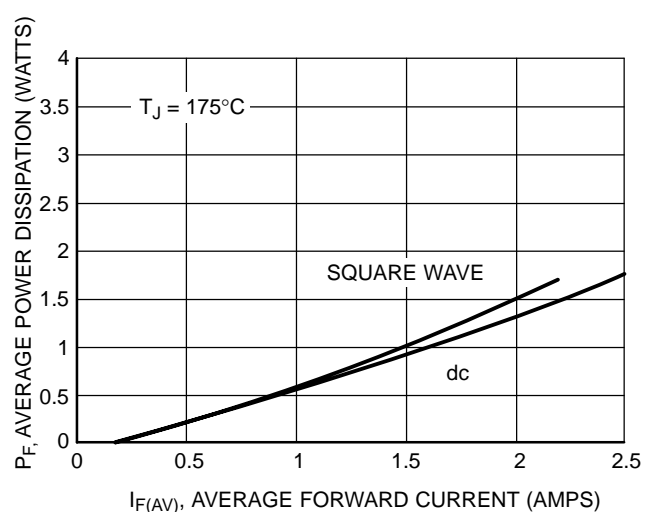
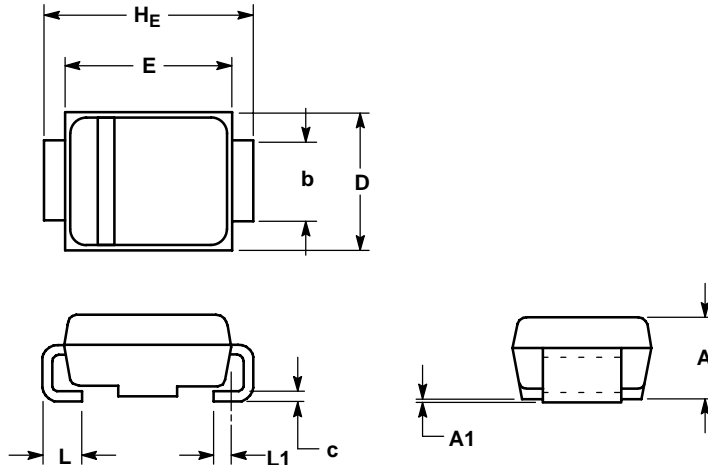


Figure 8. Power Dissipation

# MURS205T3, MURS210T3

## PACKAGE DIMENSIONS

### SMB CASE 403A-03 ISSUE F

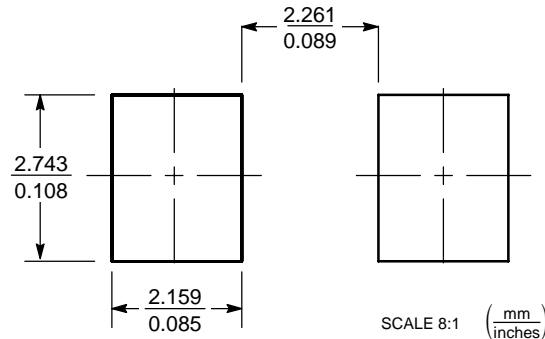


#### NOTES:


1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. D DIMENSION SHALL BE MEASURED WITHIN DIMENSION P.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	1.90	2.13	2.45	0.075	0.084	0.096
A1	0.05	0.10	0.20	0.002	0.004	0.008
b	1.96	2.03	2.20	0.077	0.080	0.087
c	0.15	0.23	0.31	0.006	0.009	0.012
D	3.30	3.56	3.95	0.130	0.140	0.156
E	4.06	4.32	4.60	0.160	0.170	0.181
HE	5.21	5.44	5.60	0.205	0.214	0.220
L	0.76	1.02	1.60	0.030	0.040	0.063
L1	0.51 REF			0.020 REF		

### SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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